

**Part Number: 47430-6415**

1.27mm Pitch Micro PGA Socket for Mobile Pentium* 4, Ball Grid Array (BGA) Mount, ZIF, 478 Circuits, Key Version B, with Mylar, Tape and Reel Package, 0.254µm Gold (Au) Plating, Cover Purple, Lead-Free



Status: **OBSOLETE**
Replacement: Contact Molex
Series: 47430
Category: Processor Sockets

Series image - Reference only

Mates With Part(s):

Intel Mobile Celeron* Processor-M, Intel Mobile Pentium* 4 Processor

Product Environmental Compliance

EU RoHS: ELV and RoHS Compliant

China RoHS:

REACH SVHC:

Low-Halogen Status: Low-Halogen

Part Detail**General**

Status	Obsolete
Category	Processor Sockets
Series	47430
Component Type	Socket
Product Name	Micro PGA

Physical

Circuits (Loaded)	479
Circuits (maximum)	479
Color - Resin	Black, Natural
Durability (mating cycles max)	20
Material - Metal	Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Nickel
Material - Resin	High Temperature Thermoplastic
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface	1.27mm
Plating min - Mating	0.254µm
Plating min - Termination	1.524µm
Temperature Range - Operating	-20°C to +90°C
Termination Interface: Style	Through Hole

Electrical**(Please review the Product Specification for specific details.)**

Current - Maximum per Contact	0.5A
Voltage - Maximum	100V

Material Info**Application Tooling**

Tooling specifications and manuals are found by selecting the products below.

Crimp Height Specifications are then contained in the Application Tooling Specification document.

Previously Available Application**Tooling**

[Check our list of old tooling that used to be available for this part](#)